



## NOTES: UNLESS OTHERWISE SPECIFIED

1. WORKMANSHIP SHALL BE IN ACCORDANCE WITH IPC-A-610.
2. ASSEMBLY PROCESS SHALL INCLUDE: REFLOW SOLDER SIDE SMD. MAXIMUM SOLDER TEMPERATURE IS 240 DEGREES CELSIUS.
3. PARTS TO OMIT WILL BE SPECIFIED ON THE BILL OF MATERIALS. LOCATIONS OF OMITTED PARTS SHALL BE FREE OF SOLDER. MASK THE SOLDER STENCIL WHERE SMT PARTS ARE OMITTED.
4. DEPANELIZE BOARDS AFTER ASSEMBLY AND ROUTE-OUT THE BREAKOUT TABS ON FOUR SIDES OF THE BOARD EDGE.
5. DO NOT APPLY ANY KIND OF ASSEMBLY STAMP OR QA STAMP TO ANY BOARD.

## REVISION HISTORY

ECO	REV	DESCRIPTION	APPR	DATE
	1	PRODUCTION	TOM G.	3-29-13

## APPROVALS

PCB DES.	HZ
APP ENG.	TOM G.
TITLE: TOP ASSEMBLY DRAWING	
DUAL 600mA MONOLITHIC, SYNCHRONOUS STEP-DOWN REGULATOR	
SIZE	IC NO. LTC3607EMSE
N/A	REV. 1
SCALE = NONE	
FILENAME: DC1847A-1.PCB	
SHT 1 OF 1	

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